EPOXIES
INNOVATIVE BONDING SOLUTIONS ETC.

20-3036 A&B
LOW DENSITY EPOXY SYNTACTIC FOAM

DESCRIPTION:
20-3036 is a light weight epoxy for potting, casting, and encapsulating electronic components and assemblies. It is formulated in a convenient 2:1 by weight mix ratio.

20-3036 can also be used for molding and fabricating light weight parts.

The engineering staff at Epoxies, Etc... is at your service to answer questions about particular requirements. Sample kits are available from stock.

FEATURES:
- Chemical, solvent and moisture resistance
- Excellent electrical insulation properties
- Outstanding thermal shock and impact resistance
- Excellent adhesion
- Easy to use low viscosity system

TYPICAL SPECIFICATIONS:
Mix Viscosity @ 25°C cps	6,000
Specific Gravity, 25°C	.75
Hardness, Shore D	70
Pot life, 100 gram mass at 25°C, minutes	60
Standard color	Grey
Dielectric constant, 60 Hz	3.70
Dielectric strength, Volts/mil	390
Volume resistivity, ohm-cm	10^{12}
Thermal conductivity, W/m- °K	0.2

Other colors available upon request.

INSTRUCTIONS FOR USE:

1. By weight, mix one part Part B catalyst to two parts Part A resin.
2. Cure overnight at room temperature or with mild heat up to 150°F.
3. Since 20-3036 contains low density fillers that will separate during storage, remix part A and part B prior to each use.

IMPORTANT:

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